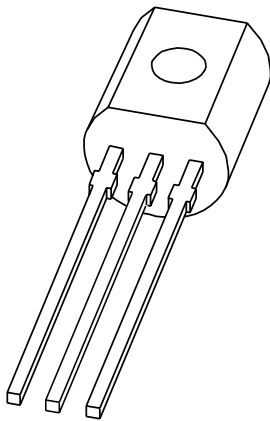


DATA SHEET



2PA1015

PNP general purpose transistor

Product specification
Supersedes data of 1999 Apr 08

2004 Oct 11

PNP general purpose transistor

2PA1015

FEATURES

- Low current (max. 150 mA)
- Low voltage (max. 50 V).

APPLICATIONS

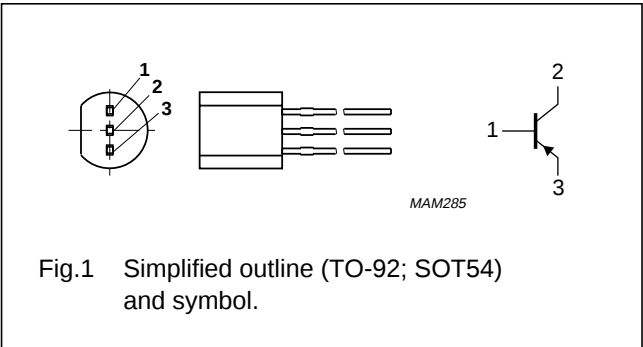
- General purpose switching and amplification.

DESCRIPTION

PNP transistor in a plastic TO-92; SOT54 package.
NPN complement: 2PC1815.

PINNING

PIN	DESCRIPTION
1	base
2	collector
3	emitter



ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
2PA1015Y	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54
2PA1015GR			

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	–50	V
V_{CEO}	collector-emitter voltage	open base	–	–50	V
V_{EBO}	emitter-base voltage	open collector	–	–5	V
I_C	collector current (DC)		–	–150	mA
I_{CM}	peak collector current		–	–200	mA
I_{BM}	peak base current		–	–200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ }^{\circ}\text{C}$; note 1	–	500	mW
T_{stg}	storage temperature		–65	+150	$^{\circ}\text{C}$
T_j	junction temperature		–	150	$^{\circ}\text{C}$
T_{amb}	ambient temperature		–65	+150	$^{\circ}\text{C}$

Note

1. Transistor mounted on an FR4 printed-circuit board.

PNP general purpose transistor

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	250	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

$T_j = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector-base cut-off current	$V_{CB} = -50\text{ V}$; $I_E = 0\text{ A}$	–	–	–100	nA
I_{EBO}	emitter-base cut-off current	$V_{EB} = -5\text{ V}$; $I_C = 0\text{ A}$	–	–	–100	nA
h_{FE}	DC current gain 2PA1015Y 2PA1015GR	$V_{CE} = -6\text{ V}$; $I_C = -2\text{ mA}$	120 200	– –	240 400	
h_{FE}	DC current gain	$V_{CE} = -6\text{ V}$; $I_C = -150\text{ mA}$	25	–	–	
V_{CEsat}	collector-emitter saturation voltage	$I_C = -100\text{ mA}$; $I_B = -10\text{ mA}$	–	–	–300	mV
V_{BEsat}	base-emitter saturation voltage	$I_C = -100\text{ mA}$; $I_B = -10\text{ mA}$	–	–	–1.1	V
C_c	collector capacitance	$V_{CB} = -10\text{ V}$; $I_E = I_C = 0\text{ A}$; $f = 1\text{ MHz}$	–	4	7	pF
f_T	transition frequency	$V_{CB} = -10\text{ V}$; $I_C = -1\text{ mA}$; $f = 100\text{ MHz}$	80	–	–	MHz
F	noise figure	$V_{CE} = -5\text{ V}$; $I_C = -200\text{ }\mu\text{A}$; $R_S = 2\text{ k}\Omega$; $f = 1\text{ kHz}$; $B = 200\text{ Hz}$	–	–	10	dB

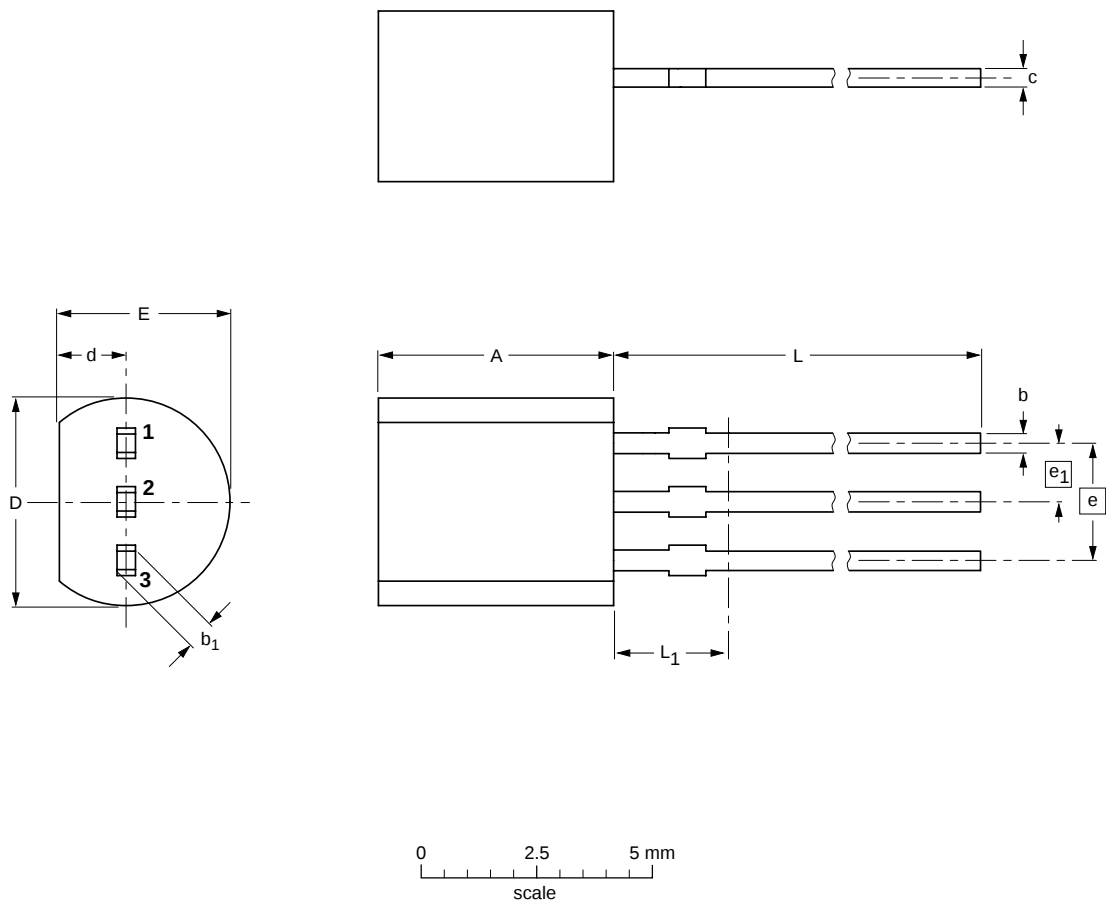
PNP general purpose transistor

2PA1015

PACKAGE OUTLINE

Plastic single-ended leaded (through hole) package; 3 leads

SOT54



DIMENSIONS (mm are the original dimensions)

UNIT	A	b	b ₁	c	D	d	E	e	e ₁	L	L ₁ ⁽¹⁾ max.
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT54		TO-92	SC-43A			-97-02-28 04-06-28

PNP general purpose transistor

2PA1015

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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